IN THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) ~~A method of attaching an identification tag to parts or sub assemblies of a semiconductor process tool,~~ The method of claim 2, further comprising:

forming a shallow cup in the part or sub assembly of the semiconductor processing tool; and

placing the identification tag in the ~~cup;~~ cup.

2. (Currently Amended) A method of employing ~~an~~ at least one identification tag ~~with parts~~ to determine the presence or absence of a part or sub ~~assemblies~~ assembly of a semiconductor process tool, comprising:

attaching the identification tag to the part or sub assembly of the semiconductor processing tool;

applying an electromagnetic signal to the identification tag, which creates a measurable dip in at least a portion of the electromagnetic signal;

determining the presence or absence of the dip; and

determining the presence or absence of the part or assembly from the presence or absence of the dip.

3. (Original) The method of claim 2, wherein the attaching includes adhering the identification tag to the part or sub assembly with adhesive.

4. (Currently Amended) The method of claim 2, wherein the attaching includes affixing the identification tag to the part or sub assembly by means of a mechanical fastener.

5. (Currently Amended) ~~A method of detecting the presence or absence of an identification tag at a location using a sensing coil, the tag being~~ The method of claim 2, wherein the identification tag is responsive to radio frequency energy, the method further comprising:

applying a swept radio frequency signal to the identification tag, wherein the identification tag alters a field strength associated with the swept radio frequency signal;

measuring a dip in the field strength through a voltage change in a sensing coil; and

determining ~~if a~~ the presence or absence of the part or assembly from the presence or absence of the dip in coil voltage ~~is present~~.

6. (Currently Amended) A method of detecting the presence or absence of a plurality of identification tags responsive to radio frequency energy, comprising:

applying a swept radio frequency signal to the plurality of identification tags;

measuring at least two dips in the swept radio frequency via a sensing coil, the at least two dips being associated with the presence of at least two from the plurality of identification tags; and

associating ~~a dip~~ at least two dips in sensing coil voltage with ~~an~~ the at least two identification ~~tag~~ tags;

wherein ~~each~~ the at least two ~~of the plurality of~~ identification tags ~~is~~ are constructed to be resonant at different frequencies.

7. (Currently Amended) A method of identifying a part or assembly in a semiconductor processing tool, the part or assembly having an identification tag attached, the tag being responsive to radio frequency energy, comprising:

applying a swept radio frequency signal to the part or assembly having an identification tag attached;

measuring a dip in the swept radio frequency via a voltage change in a sensing coil;

determining a frequency at which ~~a~~ the dip in coil voltage is present; and

determining the presence or absence of the part or assembly from the presence or absence of the dip at the frequency ~~at which the dip occurs~~.

8. (Currently Amended) A method of identifying parts or assemblies in a semiconductor processing tool, the parts or assemblies each having an identification tag attached, each identification tag be responsive to radio frequency energy, comprising:

applying a swept radio frequency signal to the parts or assemblies having identification tags attached;

measuring dips in the swept radio frequency via a voltage change in a sensing coil;

associating ~~a dip~~ the dips in sensing coil voltage ~~associated~~ with each identification tag;

wherein each of the plurality of identification tags is constructed to be resonant at different frequencies, and

determining the presence or absence of the parts or assemblies from the frequencies at which the dips occur.

9. (Currently Amended) An assembly comprising:

a part or assembly of a semiconductor processing tool; and

an identification tag attached to the part or assembly, the tag being responsive to radio frequency energy of a particular frequency,

wherein, upon application of the radio frequency energy to the identification tag, the identification tag creates a measurable dip in at least a portion of the radio frequency energy at the particular frequency so that the presence or absence of the part or assembly may be determined from the presence or absence of the dip.

10. (Currently Amended) An semiconductor processing tool comprising:

a processing chamber;

a plurality of parts or assemblies attached to or disposed in the processing chamber; and

an identification tag attached to each of the parts or assemblies, ~~each~~ at least two of the identification ~~tag~~ tags being responsive to radio frequency energy of a different frequency so that, upon application of the radio frequency energy, the identification tags create at least two measurable dips in the radio frequency energy at the different frequencies, the at least two dips being associated with the presence of at least two from the identification tags.

11. (New) The method of claim 6, wherein each identification tag is constructed to be resonant at different frequencies.

12. (New) The semiconductor processing tool of claim 10, wherein each identification tag is responsive to radio frequency energy at a different frequency.